

LISTING OF CLAIMS:

Please amend the claims as follows:

1. (Withdrawn) A film, in particular a stamping or laminating film, which includes at least one component produced using organic semiconductor technology, in particular one or more organic field effect transistors, wherein the component includes a plurality of layers and wherein the plurality of layers include electrical functional layers,

wherein one or more layers of the component are provided with a spatial structuring by means of thermal replication or UV replication, wherein at least one functional layer is partially completely severed in the region of the spatial structuring.

2. (Withdrawn) A film as set forth in claim 1, wherein the film is a stamping or laminating film.

3. (Withdrawn) A film as set forth in claim 2, wherein the stamping or laminating film comprises:

a carrier film,
at least one layer comprising an organic semiconductor element, in particular polythiophene,
at least one layer comprising an electrically insulating material, and

two or more layers which are shaped in a pattern configuration in region-wise manner and which comprise an electrically conductive material.

4. (Withdrawn) A film as set forth in claim 3, wherein the electrically conductive layers comprise an organic conductive material, in particular polyaniline or polypyrrole.

5. (Withdrawn) A film as set forth in claim 3, wherein the electrically insulating layer comprises an organic insulation material, in particular polyvinylphenol.

6. (Withdrawn) A film as set forth in claim 2, wherein the film is a stamping film which has a carrier film and a transfer layer portion which is applied to the carrier film and which is releasable from the carrier film.

7. (Withdrawn) A film as set forth in claim 6, wherein the stamping film has a release layer and an adhesive layer.

8. (Withdrawn) A film as set forth in claim 2, wherein the stamping or laminating film has one or more lacquer layers adjoining functional polymer layers.

9. (Withdrawn) A film as set forth in claim 3, wherein the electrically conductive layers, the layer comprising a semiconductor material and the layer comprising an electrically insulating material are transparent.

10. (Withdrawn) A film as set forth in claim 1, wherein the film is a film element which has a layer comprising:

an organic semiconductor material, in particular polythiophene,

a layer comprising an electrically insulating material, and

two or more layers which comprise an electrically conductive material and which are shaped in a pattern configuration in region-wise manner.

11. (Withdrawn) A film as set forth in claim 10, wherein the film is a film element which is applied to a substrate by means of a stamping or laminating film.

12. (Withdrawn) A film as set forth in claim 1, wherein an electrical functionality, in particular that of at least one electrical component produced using organic semiconductor technology, is combined with optical features.

13. (Withdrawn) A film as set forth in claim 12, wherein the film has a spatial structure which is shaped between layers of the film and which on the one hand structures in a

pattern configuration a layer of the electronic component produced using organic semiconductor technology and on the other hand generates an optical-diffraction effect as an optical feature.

14. (Withdrawn) A film as set forth in claim 13, wherein the spatial structure is formed by a superimposition of a microstructure and a macrostructure, wherein the macrostructure serves for the patterned structuring of a layer of the electronic component produced using organic semiconductor technology and the microstructure serves for the generation of the optical feature.

15. (Withdrawn) A film as set forth in claim 1, wherein the film has a holographic-optical or diffractive layer.

16. (Withdrawn) A film as set forth in claim 1, wherein the film has a thin-film layer sequence.

17. (Withdrawn) A film as set forth in claim 1, wherein the film has a decoration layer.

18. (Withdrawn) A film as set forth in claim 1, wherein the film has two or more mutually superposed layers which generate an optical security feature, wherein one or more

functional layers of the electronic component produced using organic semiconductor technology are arranged between such optically active layers.

19. (Withdrawn) A film as set forth in claim 1, wherein the film is used as a security element.

20. (Currently Amended) A process for the production of a film ~~as set forth in claim 1, wherein structuring of one or more layers of the at least one component produced using organic semiconductor technology is effected by thermal replication or UV replication~~ comprising:

producing at least one component using organic semiconductor technology, wherein the at least one component includes a plurality of layers and wherein the plurality of layers includes at least one electrical functional layer; and

spatially structuring one or more of the plurality of layers by means of thermal replication or UV replication to form a spatial structure in a replicated layer, wherein a part of at least one electrical functional layer is completely severed in the region of the spatial structure.

21. (Currently Amended) A ~~The~~ process as set forth in claim 20, wherein ~~replicated into the layer to be replicated is a~~ the spatial structure ~~whose~~ has a structure depth that is greater than or equal to the thickness of the replicated layer ~~to be replicated~~, so that the replicated layer ~~to be replicated~~ is completely severed in part by the replication operation and an electrical

functional layer which is structured in a pattern configuration in accordance with the spatial structure is formed.

22. (Currently Amended) A The process as set forth in claim 21, wherein ~~such a~~ the spatial structure is replicated in an electrode layer comprising an electrically conductive material and wherein the process further comprises applying then an electrical functional layer comprising a non-conducting or semiconducting material ~~is applied~~ to said electrode layer.

23. (Currently Amended) A process as set forth in claim 20, wherein ~~replicated into the layer to be replicated is a~~ the spatial structure whose has a structure depth that is less than the thickness of the replicated layer ~~to be replicated~~.

24. (Currently Amended) A The process as set forth in claim 23, ~~wherein there is applied further comprising applying~~ to the replicated layer an electrical functional layer of a material which upon hardening experiences a pre-defined reduction in volume, and that said material is applied to the replicated layer in an application amount with which upon hardening a functional layer which is structured in a pattern configuration in accordance with the ~~replicated~~ spatial structure remains by virtue of the shrinkage in volume.

25. (Currently Amended) A The process as set forth in claim 24, wherein the functional layer comprises an UV-hardenable material.

26. (Currently Amended) A The process as set forth in claim 23, wherein further comprising applying an electrical functional layer is applied to the replicated layer and that removing the electrical functional layer is then removed, in particular by etching, to a depth such that there remains a functional layer which is structured in a pattern configuration in accordance with the replicated spatial structure.

27. (Currently Amended) A The process as set forth in claim 23, wherein the spatial structure is replicated in an electrical functional layer comprising a non-conducting or semiconducting material and then wherein the process further comprises applying an electrode layer comprising a conductive material is applied to said electrical functional layer.

28. (Currently Amended) A The process for the production of a film as set forth in claim 1, comprising:

producing at least one component using organic semiconductor technology, wherein the at least one component includes a plurality of layers and wherein the plurality of layers includes at least one electrical functional layer; and

spatially structuring one or more of the plurality of layers by means of thermal replication or UV replication to form a spatial structure in a replicated layer, wherein a part of at least one electrical functional layer is completely severed in the region of the spatial structure,

wherein all or one or more electrode, insulation and semiconducting layers which are required for the function of the at least one component produced using organic semiconductor technology

~~are~~ at least one of the plurality of layers is introduced into a film structure having a surface area over the entire surface area or part of the surface area by a printing ~~processes~~ process.

29. (Currently Amended) A The process as set forth in claim 20, wherein an electrical functionality, ~~in particular one or more components produced using organic semiconductor technology,~~ and an optical functionality, ~~in particular diffractive optical structures,~~ are produced by a replication operation.